



**矽普**

Siliup Semiconductor

**SP30P13DP8**

30V Dual P-Channel MOSFET

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
-30V	13mΩ@-10V	-9A
	20mΩ@-4.5V	

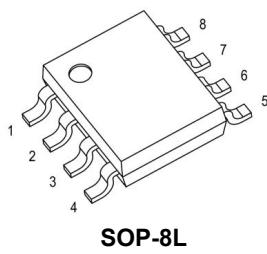
## Feature

- TrenchFET Power MOSFET
- Excellent  $R_{DS(on)}$  and Low Gate Charge

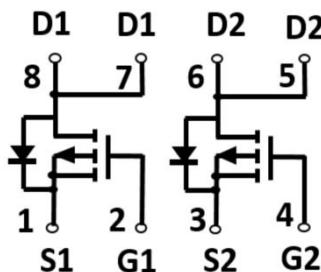
## Application

- Battery Switch
- Load switch
- Power management

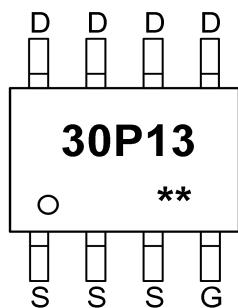
## Package



## Circuit diagram



## Marking



30P13 =Device Code  
\*\* =Week Code



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**Absolute maximum ratings (Ta=25°C unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	-30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	-9	A
Pulsed Drain Current <sup>1)</sup>	I <sub>DM</sub>	-36	A
Power Dissipation	P <sub>D</sub>	1.9	W
Thermal Resistance from Junction to Ambient <sup>2)</sup>	R <sub>θJA</sub>	65.8	°C/W
Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature	T <sub>STG</sub>	-55~+150	°C

**Electrical characteristics (T<sub>A</sub>=25 °C, unless otherwise noted)**

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-30			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V			-1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
Gate threshold voltage <sup>3)</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1	-1.5	-2.5	V
Drain-source on-resistance <sup>3)</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -10A		13	18	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -7A		20	30	
<b>Dynamic characteristics<sup>4)</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, f = 1MHz		1819		pF
Output Capacitance	C <sub>oss</sub>			254		
Reverse Transfer Capacitance	C <sub>rss</sub>			194		
<b>Switching Characteristics</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = -15V, I <sub>D</sub> = -1A, V <sub>GS</sub> = -10V, R <sub>GEN</sub> = 6Ω		10		ns
Turn-on rise time	t <sub>r</sub>			15		
Turn-off delay time	t <sub>d(off)</sub>			110		
Turn-off fall time	t <sub>f</sub>			70		
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> = -15V, V <sub>GS</sub> = -9.1V, I <sub>D</sub> = -10A		16		nC
Gate-source charge	Q <sub>gs</sub>			4.3		
Gate-drain charge	Q <sub>gd</sub>			6.1		
<b>Source-Drain Diode Characteristics</b>						
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = -9.1A, V <sub>GS</sub> = 0V			-1.2	V

**Notes:**

- 1) Repetitive rating: Pulse width limited by junction temperature.
- 2) Surface mounted on FR4 board, t≤10s.



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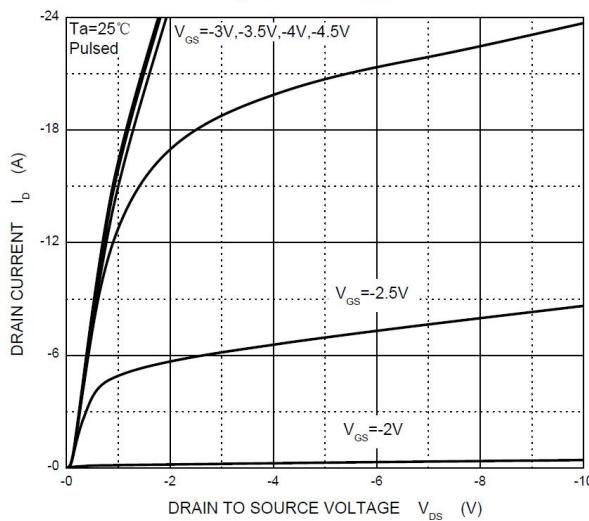
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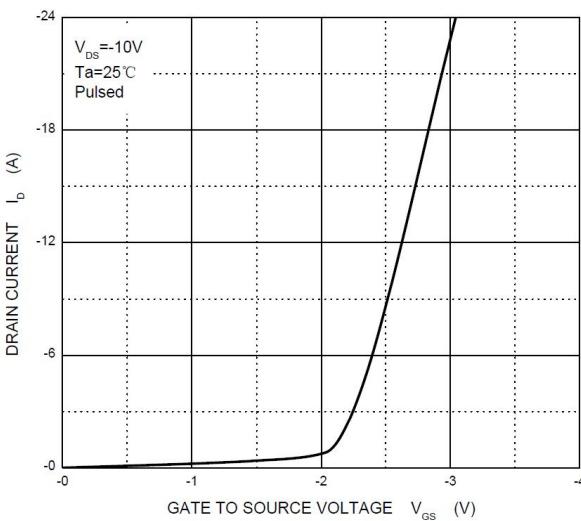
30V Dual P-Channel MOSFET

## Typical Characteristics

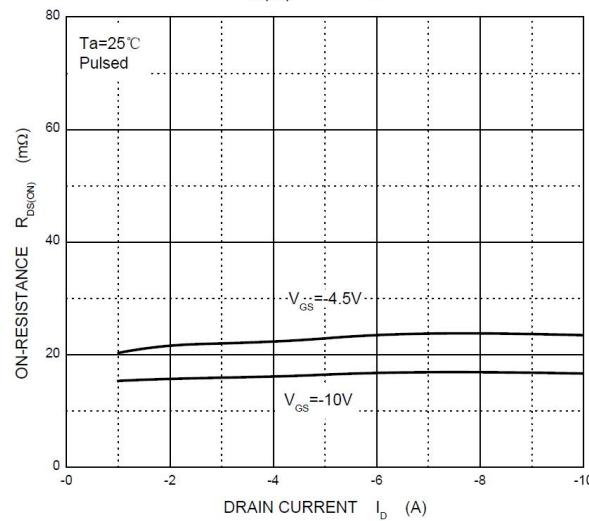
Output Characteristics



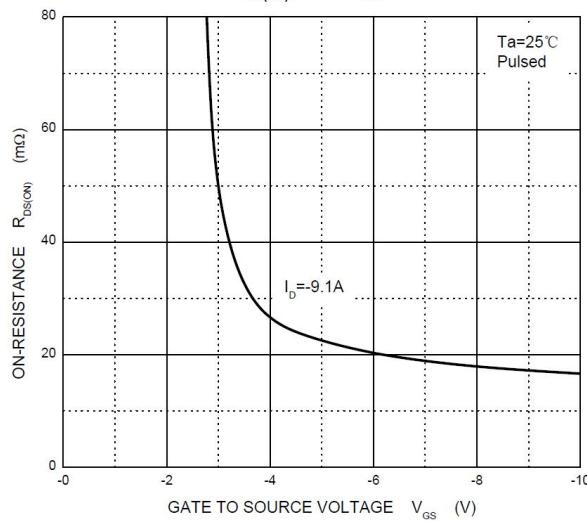
Transfer Characteristics



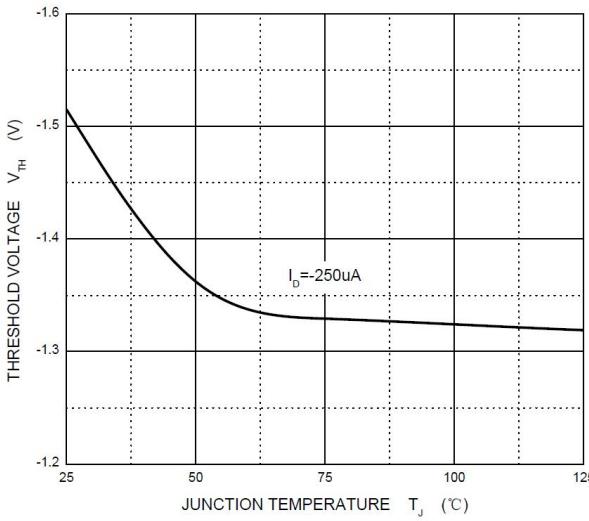
$R_{DS(ON)}$  —  $I_D$



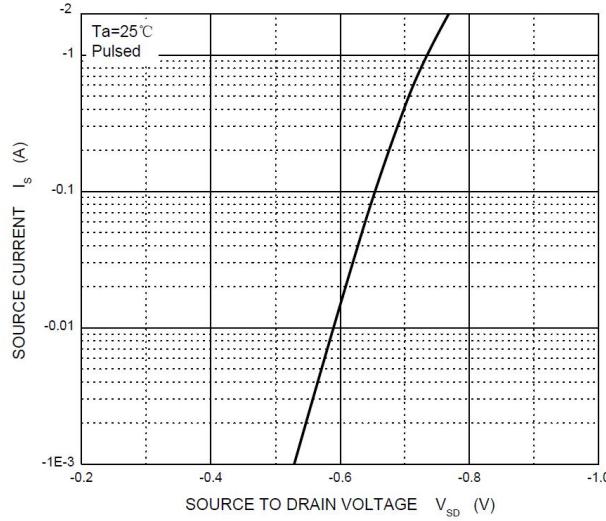
$R_{DS(ON)}$  —  $V_{GS}$



Threshold Voltage



$I_s$  —  $V_{SD}$





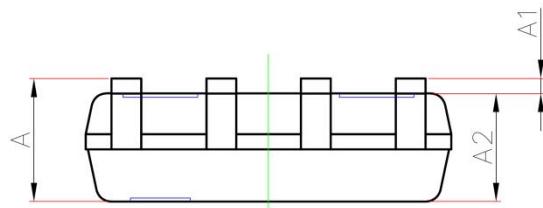
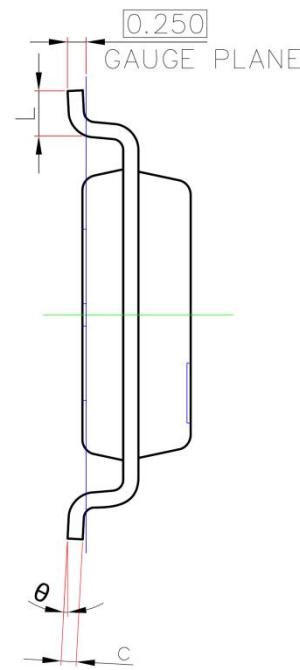
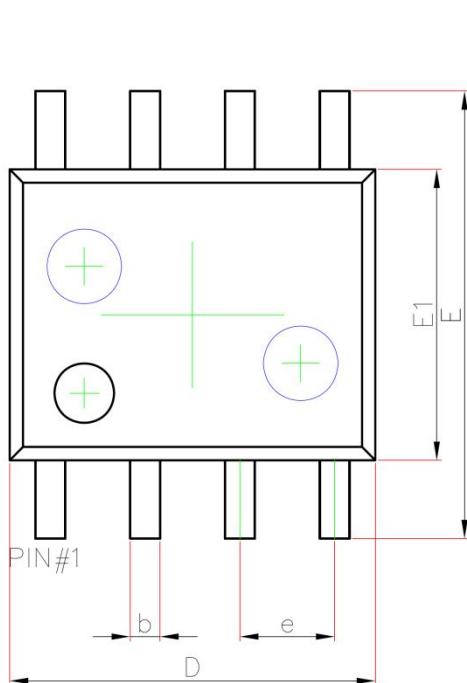
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## SOP-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.450	1.750	0.057	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.700	5.100	0.185	0.201
E	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°